

REMARKS

In the above referenced PTO communication, the Examiner stated that newly submitted claims 25-34 are directed to an invention that is independent or distinct from the invention originally claimed, because the newly submitted claims are directed to a circuit layer and an insulation layer covering part of the circuit layer, wherein the circuit layer comprises a pad, and that "the examined claims are directed to a package and does not contain the limitations of the newly submitted claims".

It is not believed by Applicant that when newly submitted claims are proposed, that previously examined claims contain all the limitations of newly submitted claims.

In response to the original Restriction Requirement of April 18, 2002, Applicant elected to have examined Claims 13-24, where independent claim 13 was for a "semiconductor device package".

In the previously added claims 25-34, now replaced by new Claims 35-44, independent claim 40 is directed to a "chip package". Since the originally elected claims 13-24 and newly added claims 40-44 are both directed to a semiconductor (or chip) package, it is believed that examination of these claims should be performed and that these claims should not be withdrawn from consideration.

Reconsideration of the withdrawal of these claims, and allowance of the present Patent Application, is therefore respectfully requested.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'SBA', with a stylized flourish extending from the end.

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